REMARKS

Claims 1-60 are pending in the present application. As will be discussed below, Claims 1 and 2 have been amended and Claims 57-60 have been added. Support for the amendment to Claim 1 is provided by, for example, original Claim 2, and support for the new claims is provided by, for example, page 20 of the specification, lines 11-15.

Claims 1-7 have been rejected under 35 U.S.C. § 112, second paragraph, as assertedly being indefinite.

In Claim 1, the phrase "as such" has been criticized as being indefinite. Additionally, Claim 2 has been criticized as been criticized as being unclear with respect to the phrase "the other resins."

In response, Applicants have amended Claims 1 and 2 to delete the phrases criticized as being indefinite.

In view of the foregoing, Applicants respectfully submit that the present claimed invention now more clearly complies with the requirements of 35 U.S.C. § 112, second paragraph. Accordingly, withdrawal of this rejection is requested.

Claims 1-7 have been rejected under 35 U.S.C. § 102(b) as anticipated by or in the alternative, under 35 U.S.C. § 103(a) as obvious over U.S. Patent No. 4,702,859 to Shimizu *et al.*

Shimizu *et al.* is relied upon to assertedly disclose an electrically conductive polyamide resin composition comprising: (A) 100 parts by weight of a polyamide resin derived from xylylenediamine as a main diamine component and an alpha, omega-linear aliphatic dicarboxylic acid as a main dicarboxylic acid component, (B) 5 to 100 parts by weight of nylon 66, (C) 30 to

300 parts by weight of glass fibers, (D) 5 to 40 parts by weight of furnace black, and (E) 5 to 40 parts by weight of graphite.

Applicants respectfully traverse this rejection for the following reasons.

In the mixed resin compound of the present claimed invention, a resin having a water absorption no higher than 0.3% is present. The low water absorption resin may be PP (polypropylene), PPE (polyphenylene ether), PPS (polyphenylene sulfide) and the like.

A mixed resin compound composed of, for example, a polyamide resin and a blending resin having a water absorption no higher than 0.3% provides a molded product which has better dimensional stability than that obtained from the polyamide resin alone. This is demonstrated by the data summarized in Table 1 of the present specification. As seen from Table 1, the water absorption and dimensional change are expressed in terms of difference between values measured before and after standing for 24 hours in a constant-temperature, constant-humidity bath at 50°C and 95 %RH. It is noted that the water absorption and dimensional stability of the molded product are greatly improved when the polyamide resin is blended with a blending resin having a low water absorption.

Shimizu discloses an electrically conductive polyamide resin composition comprising: (A) 100 parts by weight of a polyamide resin derived from xylylenediamine as a main diamine component and an alpha, omega-linear aliphatic dicarboxylic acid as a main dicarboxylic acid component, (B)5 to 100 parts by weight of nylon 66, (C)30 to 300 parts by weight of glass fibers, (D)5 to 40 parts by weight of furnace black, and (E)5 to 40 parts by weight of graphite.

However, polyamide resin (A) and (B) of Shimizu are not resins having a water absorption no higher than 0.3%, such as PP, PPE, and PPS. (Polyamide resins typically have a

higher water absorption than other resins (e.g., nylon 66 usually has a water absorption within the range of 0.6-3%, and nylon 6 usually has a water absorption within the range of 0.7-1.8%). Thus, Shimizu does not disclose a mixed resin composed of at least one resin having a water absorption no higher than 0.3%. Further, in view the data contained in the specification discussed above, Applicants respectfully submit that the any possible *prima facie* obviousness rejection based upon Shimizu has been overcome.

In view of the foregoing, Applicants respectfully submit that the present claimed invention is not anticipated or rendered *prima facie* obvious by Shimizu. Accordingly, withdrawal of this rejection is requested.

Claims 1-7 have also been rejected under 35 U.S.C. § 102(b) as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious over XP-002166020, an abstract of JP 2201811 A.

Applicants also respectfully traverse this rejection.

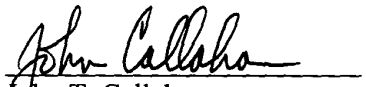
As discussed above, the present claimed invention is directed to a mixed resin compound in a desired shape formed by injection molding from a molding material containing a mixed resin composed of two or more kinds of resins differing in the rate of crystallization. At least one of the resins is a resin having a water absorption no higher than 0.3%.

Applicants respectfully submit that while XP '020 may describe a conductive resin mixture which contains polyphenylene ether, polyamide and carbon black, there is no teaching, suggestion or appreciation of the advantages of a mixed resin compound as presently claimed. Accordingly, withdrawal of this rejection is also requested.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

1. (Amended) A mixed resin compound in a desired shape formed by injection molding from a molding material containing a mixed resin composed of two or more kinds of resins differing in the rate of crystallization, wherein at least one of said resins is a resin having a water absorption no higher than 0.3% and said resins are mixed in the pellet form and the resulting mixture of pellets is injection-molded ~~as such~~.

2. (Amended) The mixed resin compound as defined in Claim 1, wherein said mixed resin comprises (A) at least one resin component selected from a polyamide resin obtained from metaxylylenediamine and adipic acid, a polyamide resin obtained from ε-caprolactam, and an ally resin obtained by blending a polyamide resin with a resin having a water absorption no higher than 0.3%~~, and (B) at least one of the other resins~~.

Claims 57-60 are added as new claims.